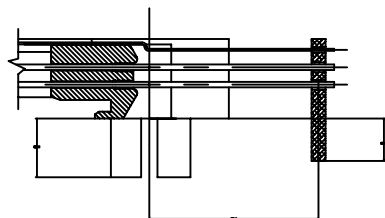
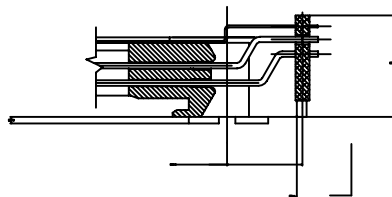


PRODUCT NO.	DIM "X"		
71249-XXXX/XXXXLF	4.25±0.1	3.5±0.1	5±0.1
	OTHERS	36,67	1,17,34, 35,51,68



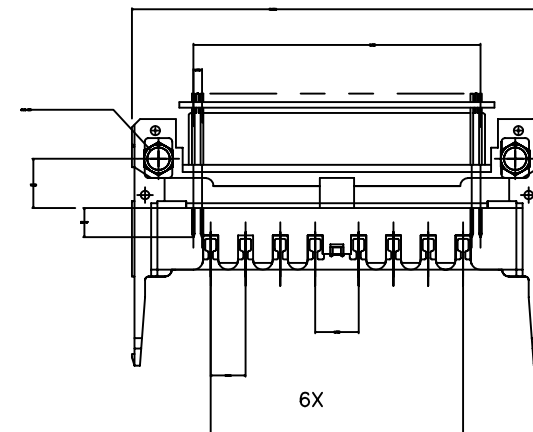
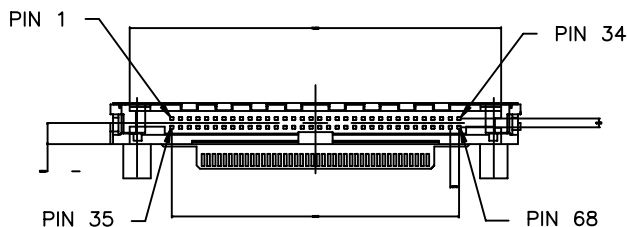
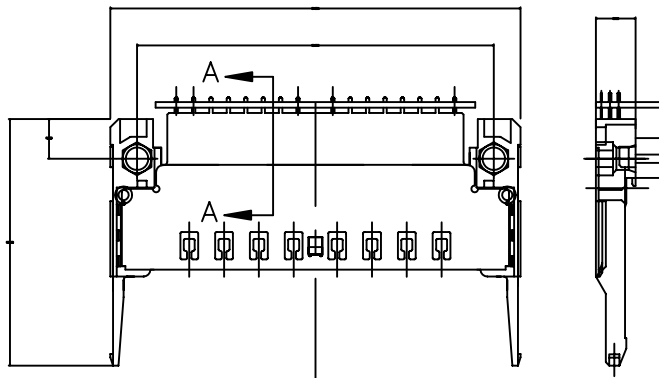
SECTION A-A
FOR ALL OTHER VERSIONS
SCALE 2/1



SECTION A-A
71249-0000/0000LF/0006/0006LF ONLY!
SCALE 2/1

71249-0640/0640LF	0	8.6	6.7
71249-0140/0140LF	0	2.8	-0.3
71249-0550/0550LF	0	9.6	6.55
71249-0050/0050LF	5.0	3.8	-0.3
71249-0543/0543LF	0	8.9	6.55
71249-0043/0043LF	4.3	3.1	-0.3
71249-0540/0540LF	0	8.6	6.55
71249-0040/0040LF	4.0	2.8	-0.3
71249-0522/0522LF	0	6.8	7.85
71249-0520/0520LF	0	6.6	7.85
71249-0200/0200LF	0	-1.4	2.8
71249-0028/0028LF	2.8	1.8	1.0
71249-0022/0022LF	2.2	1.0	1.0
71249-0022A/0022ALF	2.2	1.0	1.0
71249-0020/0020LF	2.0	0.8	1.0
71249-0506/0506LF	0	5.2	12.35
71249-0006/0006LF	0.6	-0.6	5.5
71249-0500S/0500SLF	0	4.6	12.35
71249-0000S/0000SLF	0	-1.2	5.5
71249-0500/0500LF	0	4.6	12.35
71249-0000/0000LF	0	-1.2	5.5

PRODUCT NO.	DIM K	DIM L	DIM M
		±0.10	±0.10



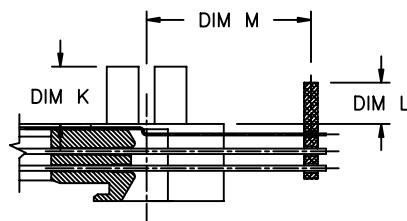
71249-X X XX XX	LEAD FREE OPTION : LF
STAND-OFF 00:	0.0mm
06:	0.6mm
22:	2.2mm
43:	4.3mm
50:	5.0mm
DECK POSITION:	0 CLOSEST TO PCB 5 FARTHEST FROM PCB
TOP MOUNT:	0
BOTTOM MOUNT:	5

NOTES:

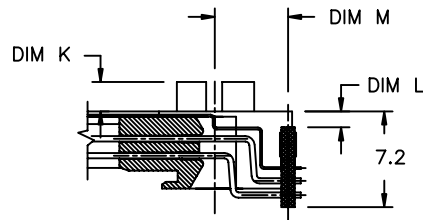
- MATERIAL
HOUSING: LIQUID CRYSTAL POLYMER (LCP) UL94V-0 BLACK
PIN: PHOSPHOR BRONZE
- FINISH
UNDER PLATING : 0.5µm MIN. Ni
CONTACT AREA : 0.1µm MIN. GOLD OVER 0.5µm MIN. Pd-Ni
SOLDER TAIL(TIN LEAD OPTION) : 2.5µm MIN. Sn-Pb
SOLDER TAIL(LEAD FREE OPTION) : 2.5µm MIN. PURE TIN
- MATING RECEPTACLE: 73277-101000/101000LF
- SEE TA-1050 FOR P.C.B. LAYOUT.
- RECOMMENDED HOLD DOWN: 2mm SCREWS (95121) AND HEX NUTS (92869).
RECOMMENDED SCREW TORQUE: 1.0 TO 1.5 MAX in-lbs (1.2-1.7 cm-kgs).
- IF LEAD FREE P/N THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION

mat'l. code				surface	tolerance	projection	product family	
				ISO 1302	ISO 406 ISO 1101		PCMCIA	
ltr	ecn no	dr	date	tolerances unless otherwise specified			title	
L	N05-0116	WB	04/26/05	angles	.X±.3	MM	CARDBUS HEADER ASS'Y	
M	N06-0220	MZ	11/07/06	linear	.XX±.13	MM	W/ VERTICAL BOARD	
				±2'	.XXX±.051	scale		
G	T10180	WL	07/02/01	dr	S.DUESTERHOEF	8/3/95	dwg no	sheet 1 of 2 size
H	T04-0273	WL	06/28/04	enrg	J.SPICKLER	8/3/95	71249	A4
J	T04-0316	WL	07/12/04	chr	J.SPICKLER	8/3/95		
K	N05-0034	WB	02/16/05	appd	J.SPICKLER	8/3/95	type	CUSTOMER Drawing
sheet	revision	M	M					
index	sheet	1	2					

PRODUCT NO.	DIM "X"		
71249-XXXX/XXXXLF	4.25±0.1	3.5±0.1	5±0.1
	OTHERS	36,67	1,17,34, 35,51,68



SECTION A-A
FOR ALL OTHER VERSIONS
SCALE 2/1

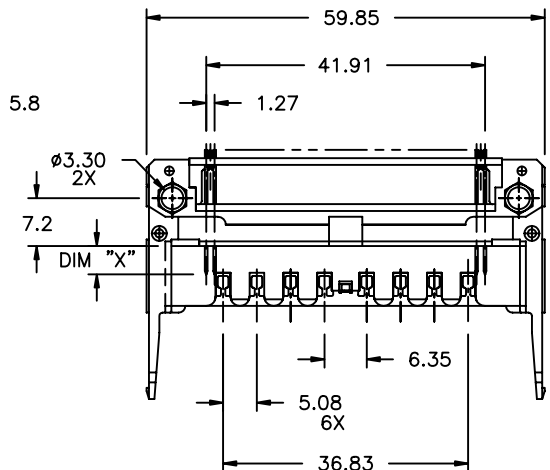
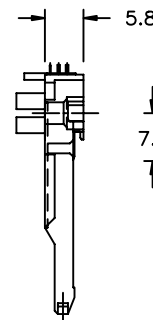
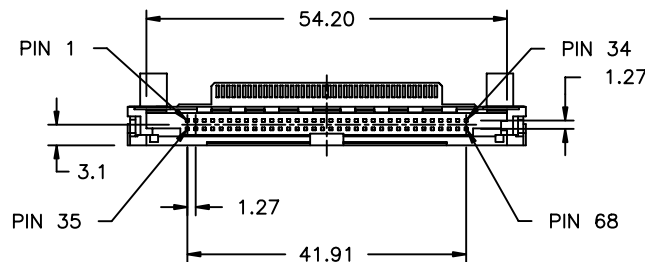
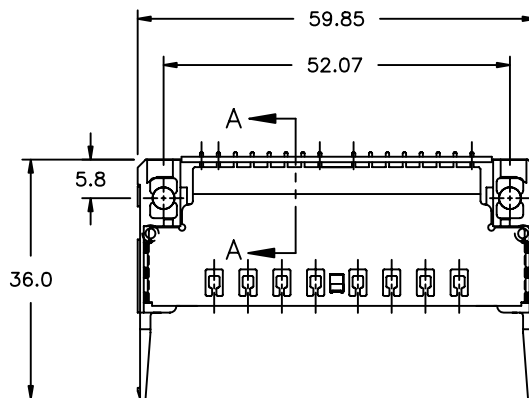


SECTION A-A
71249-5022/5022LF ONLY!
SCALE 2/1

71249-5050MLF	5.0	3.8	-0.3
71249-5622/5622LF	0	6.6	12.35
71249-5122/5122LF	2.2	0.81	5.5
71249-5550/5550LF	0	9.6	6.55
71249-5050/5050LF	5.0	3.8	-0.3
71249-5543/5543LF	0	8.9	6.55
71249-5043/5043LF	4.3	3.1	-0.3
71249-5040/5040LF	4.0	2.6	-0.3
71249-5522/5522LF	0	6.8	12.35
71249-5022/5022LF	2.2	1.0	5.5

0.0mm STAND-OFF IS NOT AVAILABLE

PRODUCT NO.	DIM K	DIM L ±0.10	DIM M ±0.10
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71249-X	X	XX	LF
LEAD-FREE :LF			
STAND-OFF 00: 0.0mm			
22: 2.2mm			
43: 4.3mm			
50: 5.0mm			
DECK POSITION: 0 CLOSEST TO PCB			
5 FARTHEST FROM PCB			
TOP MOUNT: 0			
BOTTOM MOUNT: 5			

NOTES:

- MATERIAL
HOUSING: LIQUID CRYSTAL POLYMER (LCP) UL94V-0 BLACK
PIN: COPPER ALLOY
- FINISH
UNDER PLATING : 0.5µm MIN. Ni
CONTACT AREA : 0.1µm MIN. GOLD OVER 0.5µm MIN. Pd-Ni
CONTACT AREA : 0.25µm GOLD (FOR***-MLF)
SOLDER TAIL(TIN LEAD OPTION) : 2.5µm MIN. Sn-Pb
SOLDER TAIL(LEAD FREE OPTION) : 2.5µm MIN. PURE TIN
- MATING RECEPTACLE: 73277-101000/101000LF
- SEE TA-1050 FOR P.C.B. LAYOUT.
- RECOMMENDED HOLD DOWN: 2mm SCREWS (95121) AND HEX NUTS (92869).
RECOMMENDED SCREW TORQUE: 1.0 TO 1.5 MAX in-lbs (1.2-1.7 cm-kgs).
- IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION

mat'l. code				surface	tolerance	projection	product family		
				ISO 1302	ISO 406 ISO 1101		PCMCIA		
ltr	ecn no	dr	date	tolerances unless otherwise specified			title		
M				angles	linear		CARDBUS HEADER ASS'Y W/ VERTICAL BOARD		
				±2°	.X±.3 .XX±.13 .XXX±.051	MM scale			
				dr	S.DUESTERHOEFT	8/3/95	dwg no	sheet 2of	size
				enr	J.SPICKLER	8/3/95	71249		A4
				chr	J.SPICKLER	8/3/95			
				appd	J.SPICKLER	8/3/95	type	CUSTOMER	Drawing
sheet	revision								
index	sheet								